



Material Content Data Sheet



Sales Product Name	IDV30E60C			Issued		29. August 2013		
MA#	MA000906956							
Package	PG-TO220-2-22			Weight*		2176.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.205	0.06	0.06	554	554
leadframe	non noble metal	iron	7439-89-6	1.053	0.05		484	
	inorganic material	phosphorus	7723-14-0	0.316	0.01		145	
	non noble metal	copper	7440-50-8	1051.163	48.31	48.37	483067	483696
wire	non noble metal	aluminium	7429-90-5	2.467	0.11	0.11	1134	1134
encapsulation	organic material	carbon black	1333-86-4	2.224	0.10		1022	
	plastics	epoxy resin	-	209.078	9.61		96083	
	inorganic material	silicondioxide	60676-86-0	900.816	41.40	51.11	413974	511079
leadfinish	non noble metal	tin	7440-31-5	5.465	0.25	0.25	2512	2512
plating	non noble metal	nickel	7440-02-0	1.114	0.05		512	
	inorganic material	phosphorus	7723-14-0	0.003	0.00	0.05	1	513
solder	non noble metal	antimony	7440-36-0	0.112	0.01		51	
	noble metal	silver	7440-22-4	0.279	0.01		128	
	non noble metal	tin	7440-31-5	0.726	0.03	0.05	333	512
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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